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(54) **SEMICONDUCTOR DEVICE PACKAGE AND METHOD OF MANUFACTURING THE SAME**

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(57) **ABSTRACT**

A semiconductor device package includes a substrate, a connection structure, a first package body and a first electronic component. The substrate has a first surface and a second surface opposite to the first surface. The connection structure is disposed on the first surface of the substrate. The first package body is disposed on the first surface of the substrate. The first package body covers the connection structure and exposes a portion of the connection structure. The first electronic component is disposed on the first package body and in contact with the portion of the connection structure exposed by the first package body.

